

Sputtering Pt on Si using Sputter#4

Recipe#1: Sputtering Condition: 5mT, 200W, Ar=45sccm, z=2.75, tilting=5, and time=300 s

Result: the sputtering rate≈7.4nm/min, roughness Ra=0.467nm.

Figure 1 Film Thickness=36.9nm.

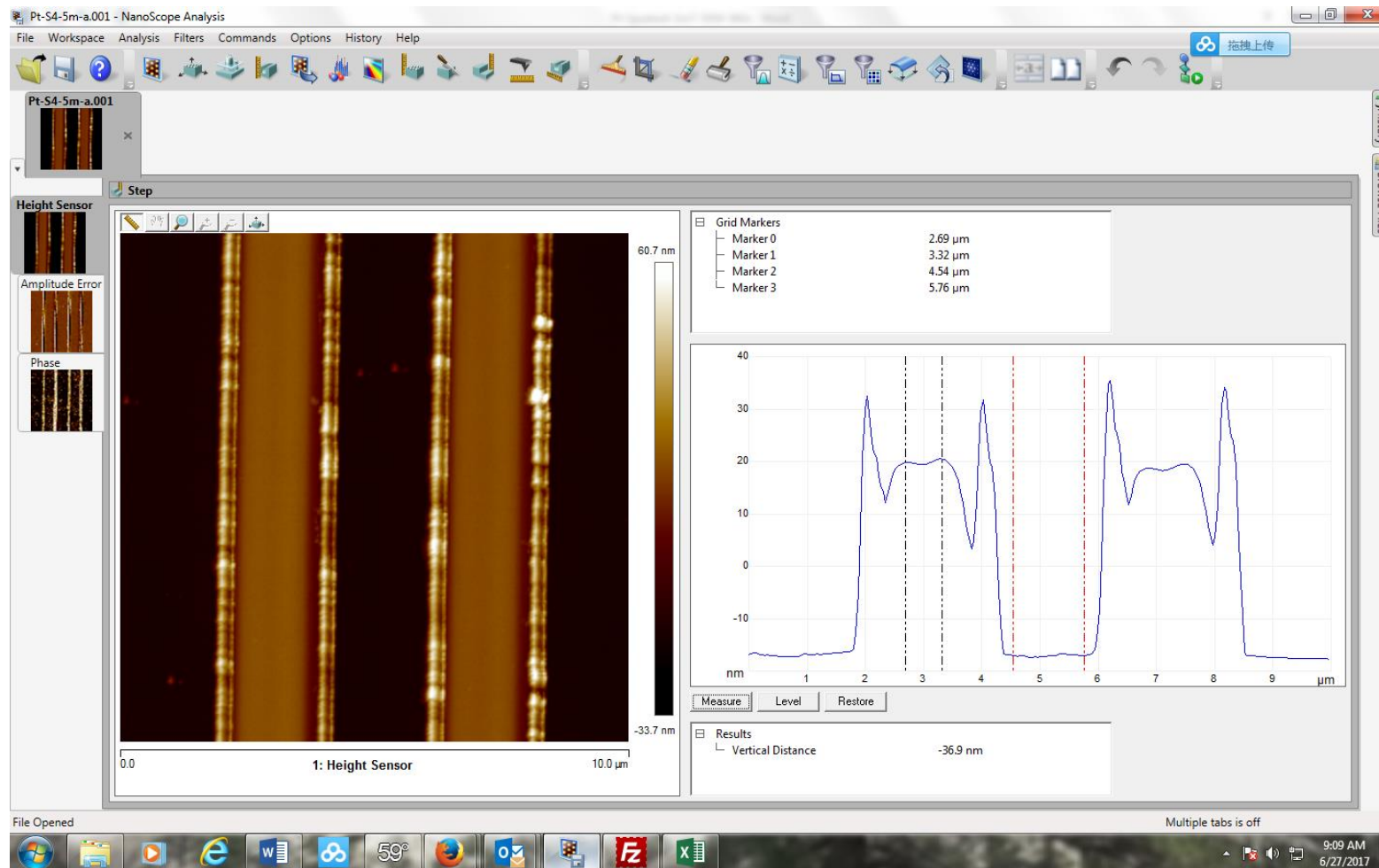
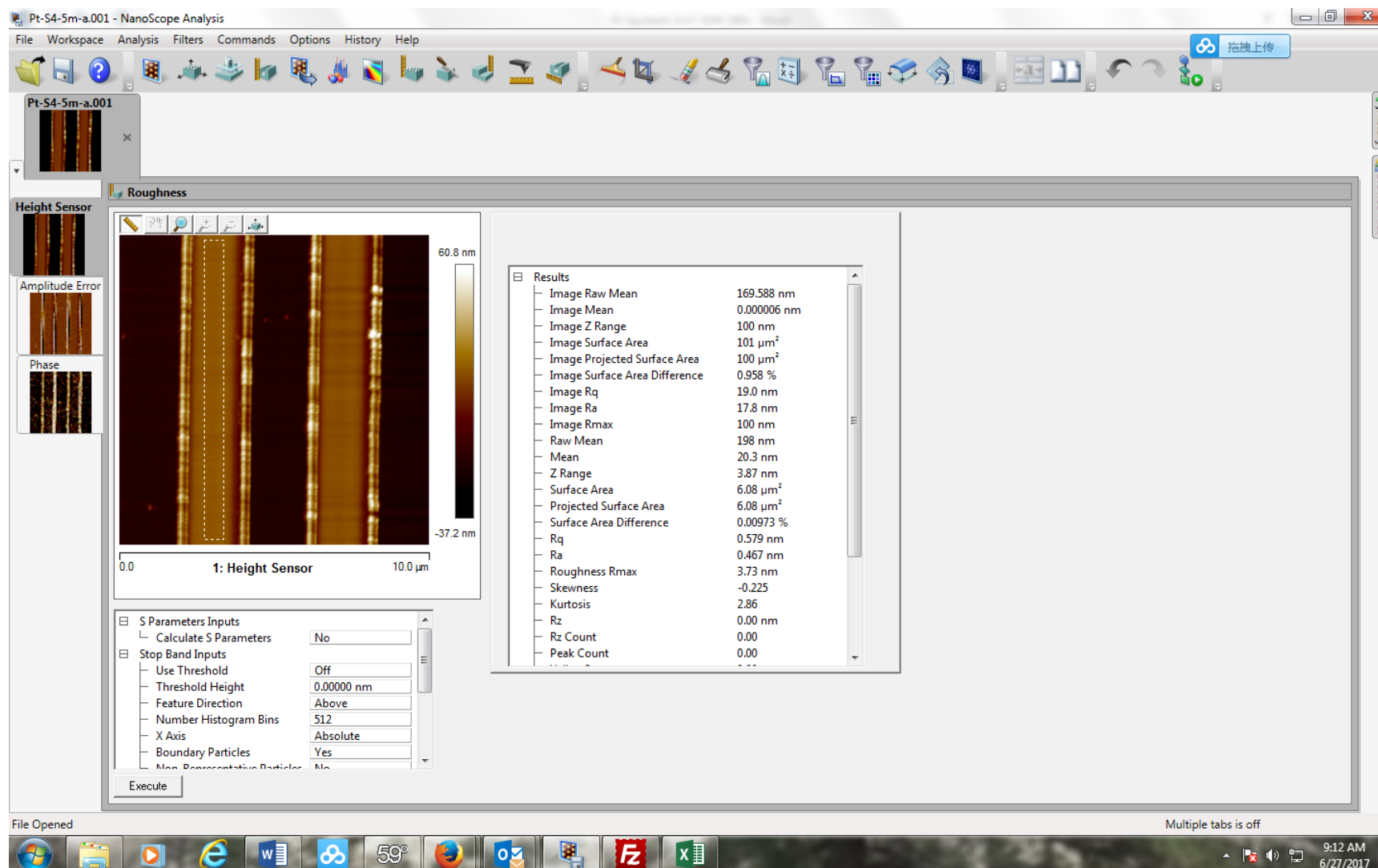


Figure 2 Surface scan by AFM (Ra=0.467 nm)



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Recipe#2: Sputtering Condition: 3mT, 50W (439v), Ar=45sccm, z=2.75, tilting=5, and time=360 s

Result: the sputtering rate≈3.9nm/min, roughness Ra=0.402nm.

Figure 3 Film Thickness=23.6nm.

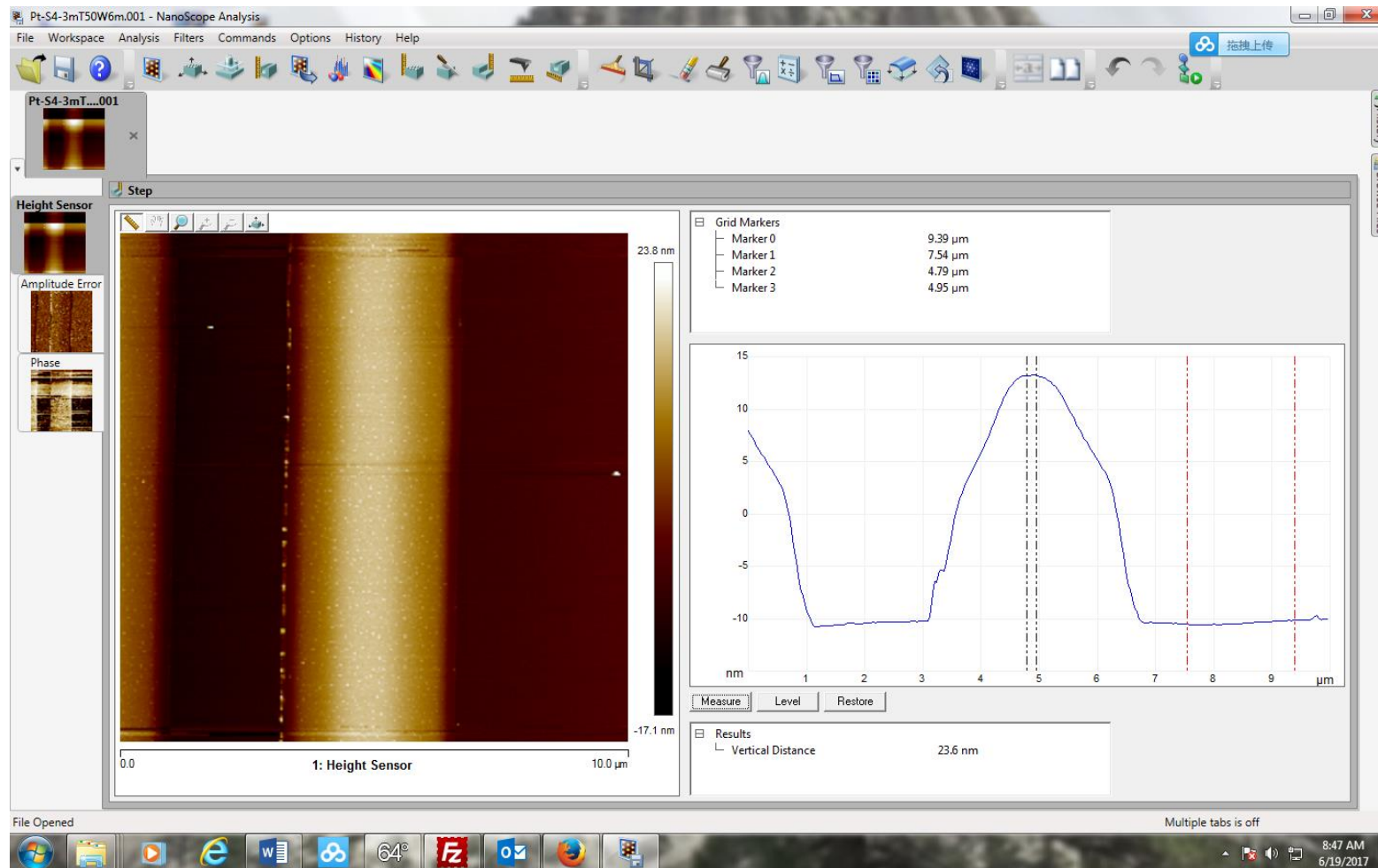


Figure 4 Surface scan by AFM (Ra=0.402 nm).

